

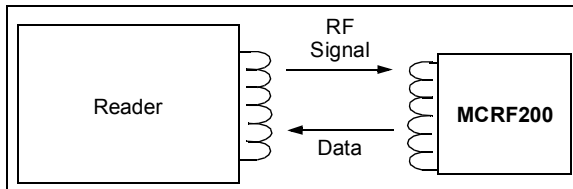
Contactless Programmable Passive RFID Device

Features

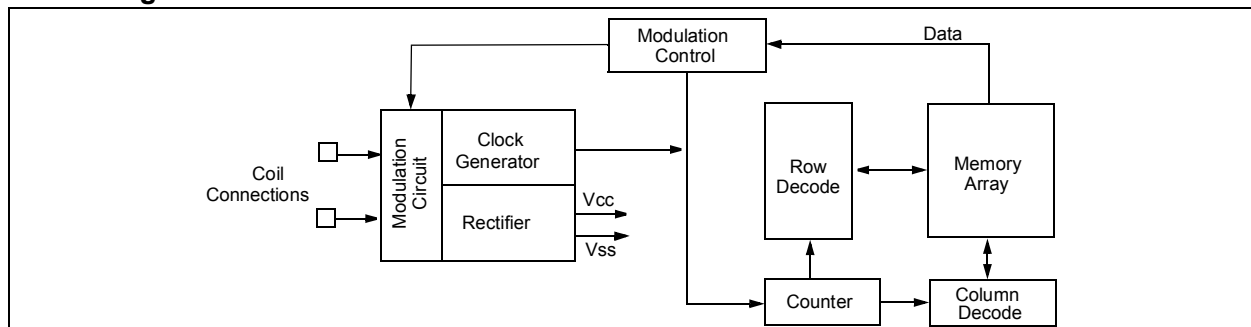
- One time contactless programmable
- Read only data transmission after programming
- 96 or 128 bits of One-Time Programmable (OTP) user memory (also supports 48 and 64-bit protocols)
- Typical operation frequency: 100 kHz - 400 kHz
- Ultra low power operation (5 μ A @ $V_{CC} = 2$ V)
- Factory programming and memory serialization (SQTP) programming available
- Modulation options:
 - ASK, FSK, PSK
- Data Encoding options:
 - NRZ Direct, Differential Biphase, Manchester Biphase
- Die, wafer, COB, PDIP, or SOIC package options
- Factory programming options

Application

- Low cost alternative for existing low frequency RFID devices
- Access control and time attendance
- Security systems
- Animal tagging
- Leisure product identification
- Industrial tagging
- Inventory control

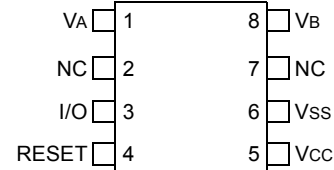


Block Diagram



Package Type

PDIP/SOIC



Note: Pins 3, 4, 5, and 6 are for device test purposes only, Pins 1 and 8 are for antenna connections.
DO NOT ground pin 5.

Description

The MCRF200 is a passive Radio Frequency Identification (RFID) device for low frequency applications (100 kHz - 400 kHz). The device is powered by rectifying an incoming RF signal from the reader. The device requires an external LC resonant circuit to receive the incoming RF signal and to send data. The device develops a sufficient DC voltage for operation when its external coil voltage reaches approximately 10Vpp.

The device has a total of 128 bits of user programmable memory and an additional 12 bits for the configuration register. The user can program the 128 bits of user memory by a contactless programmer with a special programming pulse sequence. The memory can be also factory programmed prior to shipment to the customer. The device is a One-Time Programmable (OTP) integrated circuit and operates as a read only device after programming.

MCRF200

The configuration register includes options for communication protocol (ASK, FSK, PSK), data encoding method, data rate, and data length. These options are specified by customer and factory programmed during assembly. Because of its many choices of configuration options, the device can be easily used as an alternative or second source for most of the existing low frequency passive RFID devices available today.

The device has a modulation transistor between the two antenna connections (VA and VB). The modulation transistor damps or undamps the coil voltage when it sends data. The variation of coil voltage controlled by the modulation transistor results in a perturbation of voltage in reader antenna coil. By monitoring the changes in reader coil voltage, the data transmitted from the device can be reconstructed.

The device is available in die, wafer, Chip-on-Board (COB) modules, PDIP, or SOIC packages. Factory programming and memory serialization (SOTP) are also available upon request. See TB023 for more information on contact programming support.

The DV103001 developer's kit includes Contactless Programmer, ASK, FSK, PSK reference readers, and reference design guide. The reference design guide includes schematics for readers and contactless programmer as well as in-depth document for antenna circuit designs.

1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings*

Storage temperature - 65°C to +150°C

Ambient temp. with power applied -40°C to +125°C

Maximum current into coil pads 50 mA

***Notice:** Stresses above those listed under "Maximum ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 1-1: AC AND DC CHARACTERISTICS

| All parameters apply across the specified operating ranges unless otherwise noted. | | Industrial (I): T _{AMB} = -40°C to +85°C | | | | |
|--|------|---|-----|-----|-----------------|-----------------------|
| Parameter | Sym | Min | Typ | Max | Units | Conditions |
| Clock frequency | FCLK | 100 | — | 400 | kHz | |
| Contactless programming time | TWC | — | 2 | — | sec | For all 128-bit array |
| Data retention | | 200 | — | — | Years | at 25°C |
| Coil current (Dynamic) | ICD | — | 50 | | μA | |
| Operating current | IDD | — | 5 | | μA | V _{CC} = 2V |
| Turn-on-voltage (Dynamic) for modulation | VAVB | 10 | — | — | V _{PP} | |
| | VCC | 2 | — | — | V _{DC} | |
| Input Capacitance | CIN | — | 2 | — | pF | Between VA and VB |

2.0 FUNCTIONAL DESCRIPTION

The device contains three major building blocks. They are RF front-end, configuration and control logic, and memory sections. The Block Diagram is shown on page 1.

2.1 RF Front-End

The RF front-end of the device includes circuits for rectification of the carrier, V_{DD} (operating voltage), and high-voltage clamping. This section also includes a clock generator and modulation circuit.

2.1.1 RECTIFIER – AC CLAMP

The rectifier circuit rectifies RF voltage on the external LC antenna circuit. Any excessive voltage on the tuned circuit is clamped by the internal circuitry to a safe level to prevent damage to the IC.

2.1.2 POWER-ON RESET

This circuit generates a power-on reset when the tag first enters the reader field. The reset releases when sufficient power has developed on the V_{DD} regulator to allow correct operation.

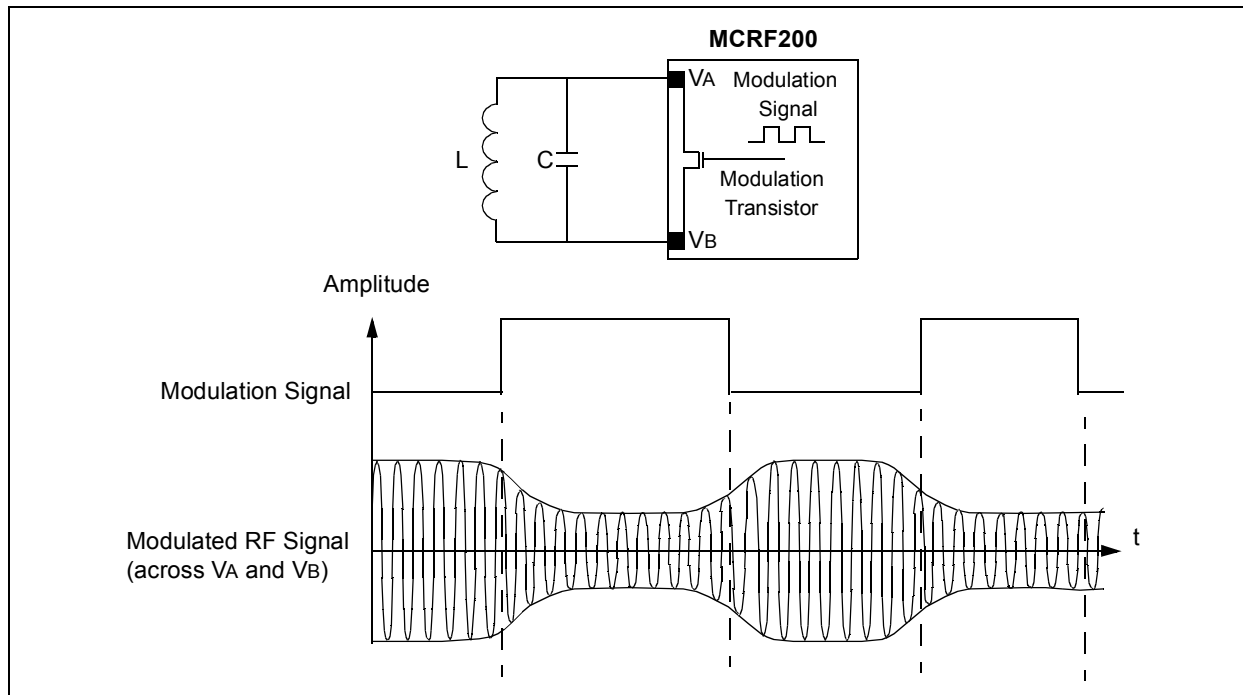
2.1.3 CLOCK GENERATOR

This circuit generates a clock based on the carrier frequency from the reader. This clock is used to derive all timing in the device, including the baud rate and modulation rate.

2.1.4 MODULATION CIRCUIT

The device sends the encoded data to the reader by AM-modulating the coil voltage across the tuned LC circuit. A modulation transistor is placed between the two antenna coil pads (V_A and V_B). The transistor turns on and off based on the modulation signal. As a result, the amplitude of the antenna coil voltage varies with the modulation signal. See Figure 2-1 for details.

FIGURE 2-1: MODULATION SIGNAL AND MODULATED SIGNAL



2.2 Configuration Register and Control Logic

The configuration register determines the operational parameters of the device. The configuration register can not be programmed contactlessly; it is programmed during wafer probe at the Microchip factory. CB11 is always a zero; CB12 is set when successful contact or contactless programming of the data array has been completed. Once CB12 is set, device programming and erasing is disabled. Table 2-1 contains a description of the bit functions of the control register.

2.2.1 BAUD RATE TIMING OPTION

The chip will access data at a baud rate determined by bits CB2, CB3, and CB4 of the configuration register. For example, MOD32 (CB2 = 0, CB3 = 1, CB4 = 1) has 32 RF cycles per bit. This gives the data rate of 4 kHz for the RF carrier frequency of 128 kHz.

The default timing is MOD128 (FCLK/128), and this mode is used for contact and contactless programming. Once the array is successfully programmed, the lock bit CB12 is set. When the lock bit is set, programming and erasing the device becomes permanently disabled. The configuration register has no effect on device timing until the EEPROM data array is programmed (CB12 = 1).

2.2.2 DATA ENCODING OPTION

This logic acts upon the serial data being read from the EEPROM. The logic encodes the data according to the configuration bits CB6 and CB7. CB6 and CB7 determine the data encoding method. The available choices are:

- Non-return to zero-level (NRZ_L)
- Biphasic Differential, Biphasic Manchester
- Inverted Manchester

2.2.3 MODULATION OPTION

CB8 and CB9 determine the modulation protocol of the encoded data. The available choices are:

- ASK
- FSK
- PSK_1
- PSK_2

When ASK (direct) option is chosen, the encoded data is fed into the modulation transistor without change.

When FSK option is chosen, the encoded data is represented by:

- a. Sets of 10 RF carrier cycles (first 5 cycles → higher amplitude, the last 5 cycles → lower amplitude) for logic “high” level.
- b. Sets of 8 RF carrier cycles (first 4 cycles → higher amplitude, the last 4 cycles → lower amplitude) for logic “low” level.

For example, FSK signal for MOD40 is represented:

- a. 4 sets of 10 RF carrier cycles for data ‘1’.
- b. 5 sets of 8 RF carrier cycles for data ‘0’.

Refer to Figure 2-2 for the FSK signal with MOD40 option.

The PSK_1 represents change in the phase of the modulation signal at the change of the encoded data. For example, the phase changes when the encoded data is changed from ‘1’ to ‘0’, or from ‘0’ to ‘1’.

The PSK_2 represents change in the phase at the change on ‘1’. For example, the phase changes when the encoded data is changed from ‘0’ to ‘1’, or from ‘1’ to ‘1’.

FIGURE 2-2: ENCODED DATA AND FSK OUTPUT SIGNAL FOR MOD40 OPTION

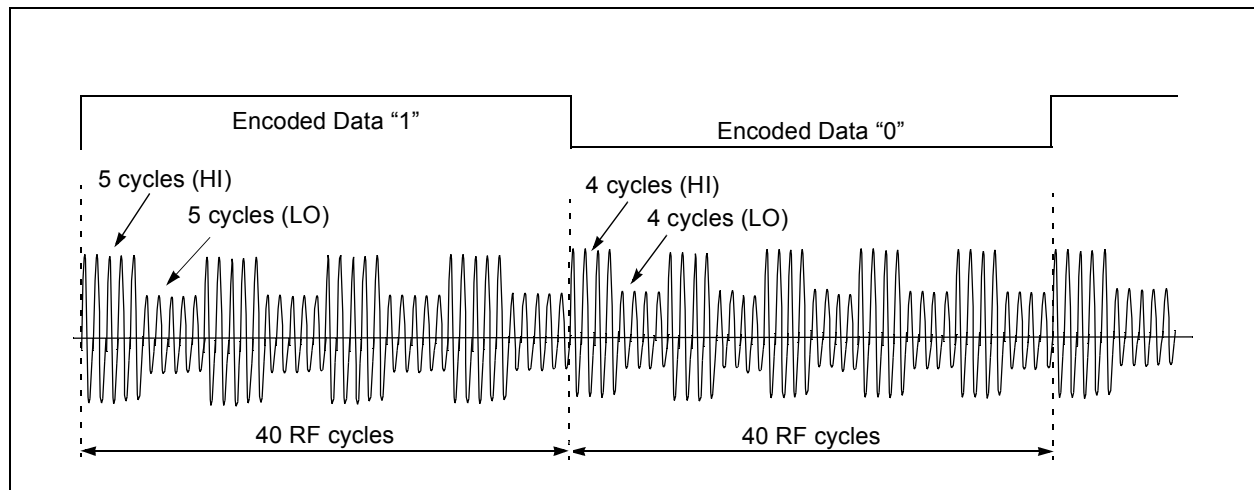
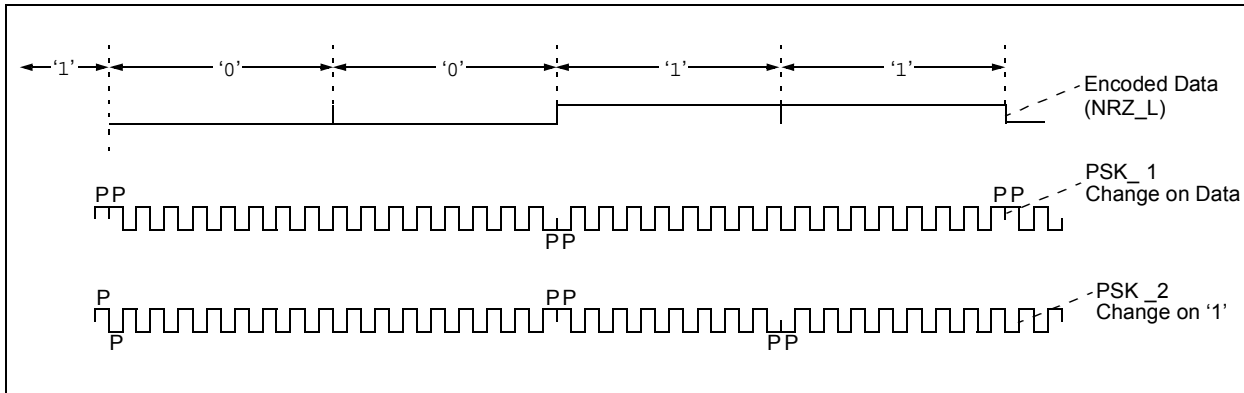


FIGURE 2-3: PSK DATA MODULATION



2.2.4 MEMORY ARRAY LOCK BIT (CB12)

The CB12 must be '0' for contactless programming (Blank). The bit (CB12) is automatically set to '1' as soon as the device is programmed contactlessly.

2.3 Memory Section

The device has 128 bits of one-time-programmable (OTP) memory. The user can choose 96 or 128 bits by selecting the CB1 bit in the configuration register. See Table 2-1 for more details.

2.3.1 COLUMN AND ROW DECODER LOGIC AND BIT COUNTER

The column and row decoders address the EEPROM array at the clock rate and generate a serial data stream for modulation. This data stream can be up to 128 bits in length. The size of the data stream is user programmable with CB1 and can be set to 96 or 128 bits. Data lengths of 48 and 64 bits are available by programming the data twice in the array, end-to-end.

The column and row decoders route the proper voltage to the array for programming and reading. In the programming modes, each individual bit is addressed serially from bit 1 to bit 128.

2.4 Examples of Configuration Settings

EXAMPLE 2-1: "08D" Configuration

The "08D" (hex) configuration is interpreted as follows:

CB12 CB1
 "08D" → 0000-1000-1101

Referring to Table 2-1, the "08D" configuration represents:

Modulation = PSK_1
 PSK rate = $rf/2$
 Data encoding = NRZ_L (direct)
 Baud rate = $rf/32 = \text{MOD}32$
 Memory size 128 bits

EXAMPLE 2-2: "00A" Configuration

The "00A" (hex) configuration is interpreted as follows:

CB12 CB1
 "00A" → 0000-0000-1010

The MSB corresponds to CB12 and the LSB corresponds to CB1 of the configuration register. Therefore, we have:

| | | | |
|--------|--------|--------|-------|
| CB12=0 | CB11=0 | CB10=0 | CB9=0 |
| CB8=0 | CB7=0 | CB6=0 | CB5=0 |
| CB4=1 | CB3=0 | CB2=1 | CB1=0 |

Referring to Table 2-1, the "00A" configuration represents:

Not programmed device (blank), anticollision: disabled, FSK protocol, NRZ_L (direct) encoding, MOD50 (baud rate = $rf/50$), 96 bits.

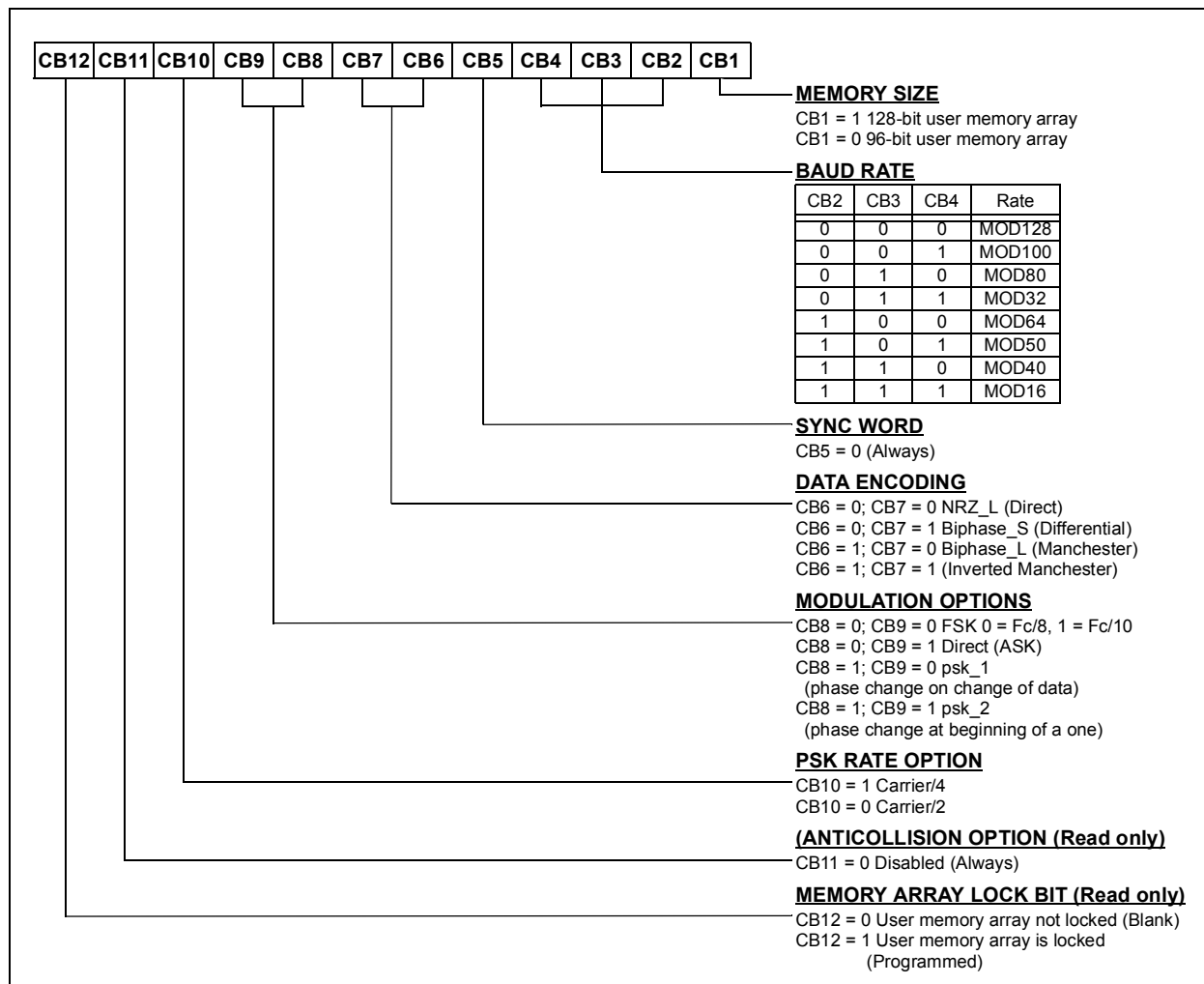
EXAMPLE 2-3: MCRF200 Configuration for FDX-B ISO Animal Standard Protocol (ASP)

The FDX-B ISO Specification is:

Modulation = ASK
 Data encoding = Differential biphase
 Baud rate = $rf/32 = 4 \text{ kbits/sec}$ for 128 kHz
 Memory size = 128 bits

Referring to Table 2-1, the equivalent MCRF200 configuration is: "14D".

TABLE 2-1: CONFIGURATION REGISTER



MCRF200

3.0 MODES OF OPERATION

The device has two basic modes of operation: Native Mode and Read Mode.

3.1 Native Mode

Unprogrammed blank device (CB12=0) is operated in native mode:

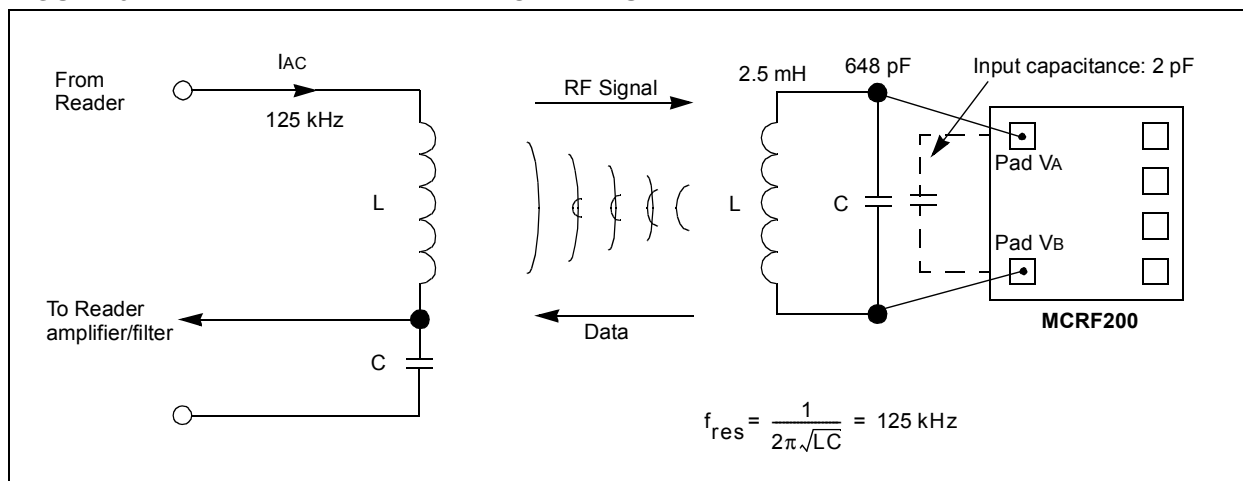
FCLK/128, FSK, NRZ_L (direct)

Refer to Figure 4-1 for contactless programming sequence. Also see the microID 125 kHz Design Guide (DS51115) for more information.

3.2 Read Mode

After the device is programmed (CB12=1), the device is operated in the read only mode. The device transmits its data according to the protocol in the configuration register.

FIGURE 3-1: TYPICAL APPLICATION CIRCUIT



4.0 CONTACTLESS PROGRAMMING

The contactless programming of the device is possible for blank devices (CB12=0) only. The contactless programming timing sequence consists of:

- a. RF Power-up signal.
- b. Short gap (absence of RF field).
- c. Verify signal (continuous RF signal).
- d. Programming signal.
- e. Device response with programmed data.

The blank device (CB12=0) understands the RF power-up followed by a gap as a blank checking command, and outputs 128 bits of FSK data with all '1's after the short gap. To see this blank data (verify), the reader/programmer must provide a continuous RF signal for 128 bit-time. (The blank (unprogrammed) device has all 'F's in its memory array. Therefore, the blank data should be all '1's in FSK format). Since the blank device operates at default mode (MOD128), there are 128 RF cycles for each bit. Therefore, the time requirement to complete this verify is 128 bits x 128 RF cycles/bit x 8 use/cycles = 131.1 msec for 125 kHz signal.

As soon as the device completes the verify, it enters the programming mode. The reader/programmer must provide RF programming data right after the verify. In this programming mode, each bit lasts for 128 RF cycles. Refer to Figure 4-1 for the contactless programming sequence.

Customer must provide the following specific voltage for the programming:

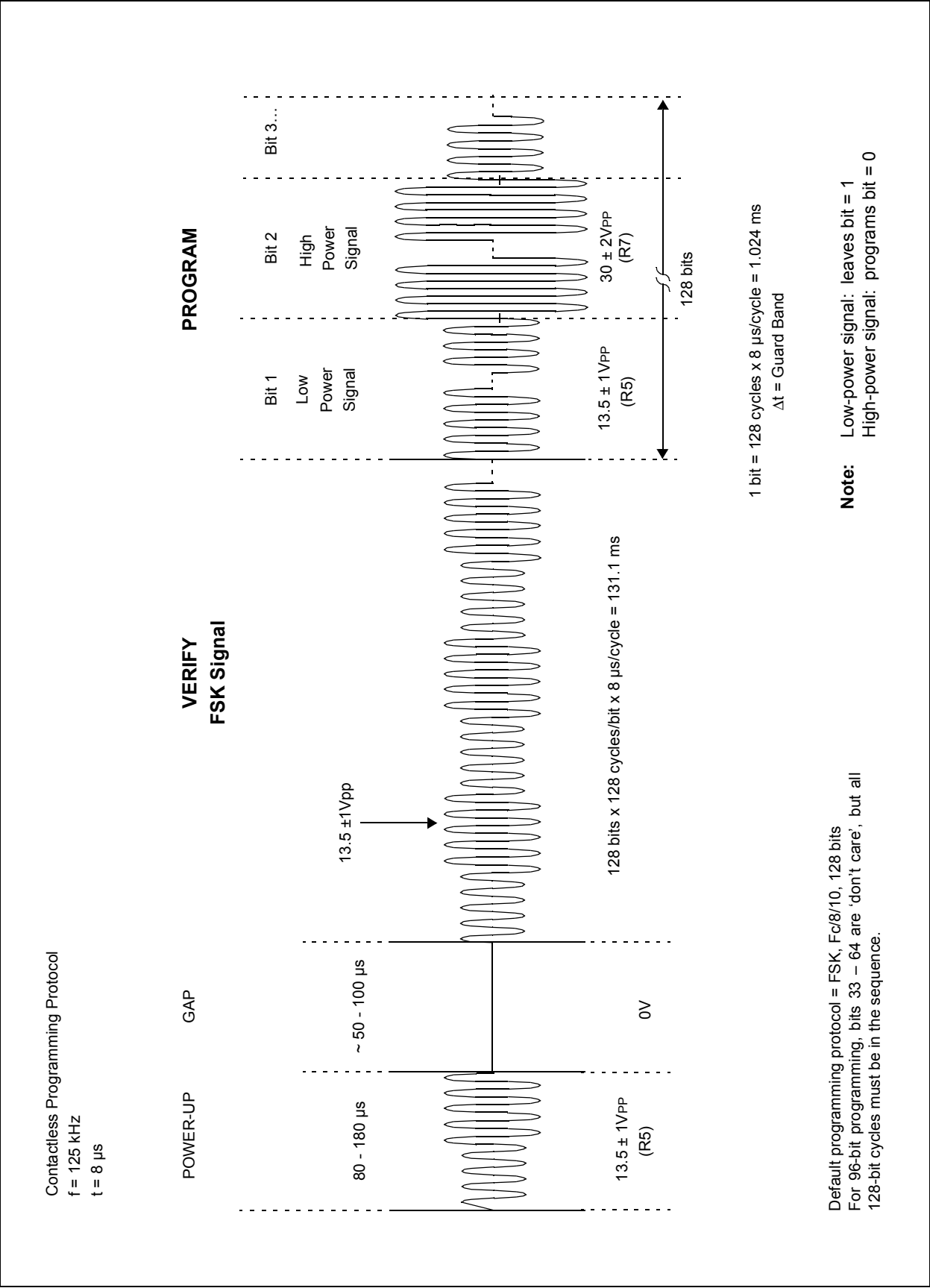
1. Power-up and verify signal = 13.5V \pm 1Vpp
2. Programming voltage:
 - To program bit to '1': 13.5V \pm 1Vpp
 - To program bit to '0': 30V \pm 2Vpp

After the programming cycle, the device outputs programmed data (response). The reader/programmer can send the programming data repeatedly after the device response until the programming is successfully completed. The device locks the CB12 as soon as the programming mode (out of field) is exited and becomes a read-only device.

Once the device is programmed (CB12=1), the device outputs its data according to the configuration register.

The PG103001 (Contactless Programmer) is used for the programming of the device. The voltage level shown in Figure 4-1 is adjusted by R5 and R7 in the contactless programmer. Refer to the MicroID 125 kHz Design Guide (DS51115) for more information.

FIGURE 4-1: CONTACTLESS PROGRAMMING SEQUENCE



5.0 MECHANICAL SPECIFICATIONS FOR DIE AND WAFER

FIGURE 5-1: DIE PLOT

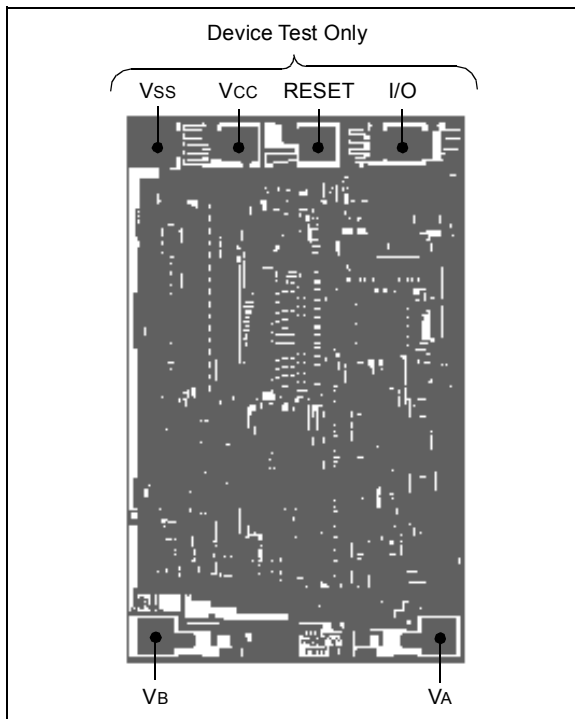


TABLE 5-1: PAD COORDINATES (μm)

| Pad Name | Passivation Openings | | Pad Center X | Pad Center Y |
|----------|----------------------|------------|--------------|--------------|
| | Pad Width | Pad Height | | |
| VA | 90.0 | 90.0 | 427.50 | -734.17 |
| VB | 90.0 | 90.0 | -408.60 | -734.17 |

Note 1: All coordinates are referenced from the center of the die.

Note 2: Die size: 1.1215 mm x 1.7384 mm.
44.15 mils x 68.44 mils

TABLE 5-2: PAD FUNCTION TABLE

| Name | Function |
|-------|---|
| VA | Antenna Coil connection |
| VB | |
| Vss | For device test only Do Not Connect to Antenna |
| Vcc | |
| RESET | |
| I/O | |

TABLE 5-3: DIE MECHANICAL DIMENSIONS

| Specifications | Min | Typ | Max | Unit | Comments |
|--|-----|----------------------|-------------|-----------|--|
| Bond pad opening | — | 3.5 x 3.5 89 x 89 | — | mil μm | Note 1, Note 2 |
| Die backgrind thickness | — | 7 177.8 | — | mil μm | Sawed 6" wafer on frame (option = WF) Note 3 |
| | — | 11 279.4 | — | mil μm | Unsauced wafer (option = W) Note 3 |
| Die backgrind thickness tolerance | — | — | ±1 ±25.4 | mil μm | Note 4 |
| Die passivation thickness (multilayer) | — | 0.9050 | — | μm | Note 5 |
| Die Size: | | | | | |
| Die size X*Y before saw (step size) | — | 44.15 x 68.44 | — | mil | — |
| Die size X*Y after saw | — | 42.58 x 66.87 | — | mil | — |

Note 1: The bond pad size is that of the passivation opening. The metal overlaps the bond pad passivation by at least 0.1 mil.

Note 2: Metal Pad Composition is 98.5% Aluminum with 1% Si and 0.5% Cu.

Note 3: As the die thickness decreases, susceptibility to cracking increases. It is recommended that the die be as thick as the application will allow.

Note 4: This specification is not tested. For design guidance only.

Note 5: The Die Passivation thickness (0.905 μm) can vary by device depending on the mask set used. The passivation is formed by:

- Layer 1: Oxide (undoped oxide 0.135 μm)
- Layer 2: PSG (doped oxide, 0.43 μm)
- Layer 3: Oxynitride (top layer, 0.34 μm)

Note 6: The conversion rate is 25.4 μm/mil.

MCRF200

Notice: Extreme care is urged in the handling and assembly of die products since they are susceptible to mechanical and electrostatic damage.

TABLE 5-4: WAFER MECHANICAL SPECIFICATIONS

| Specifications | Min | Typ | Max | Unit | Comments |
|---------------------------|-----|-------|-----|-------|----------|
| Wafer Diameter | — | 6 | — | inch | 150 mm |
| Die separation line width | — | 80 | — | μm | |
| Dice per wafer | — | 8,000 | — | die | |
| Batch size | — | 24 | — | wafer | |

6.0 FAILED DIE IDENTIFICATION

Every die on the wafer is electrically tested according to the datasheet specifications and visually inspected to detect any mechanical damage such as mechanical cracks and scratches.

Any failed die in the test or visual inspection is identified by black colored ink. Therefore, any die covered with black ink should not be used.

The ink dot specification:

- Ink dot size: minimum 20 μm x 20 μm
- Position: central third of die
- Color: black

7.0 WAFER DELIVERY DOCUMENTATION

Each wafer container is marked with the following information:

- Microchip Technology Inc. MP Code
- Lot Number
- Total number of wafers in the container
- Total number of good dice in the container
- Average die per wafer (DPW)
- Scribe number of wafers with number of good dice

8.0 NOTICE ON DIE AND WAFER HANDLING

The device is very susceptible to Electro-Static Discharge (ESD). ESD can cause critical damage to the device. Special attention is needed during the handling process.

Any ultraviolet (UV) light can erase the memory cell contents of an unpackaged device. Fluorescent lights and sun light can also erase the memory cell although it takes more time than UV lamps. Therefore, keep any unpackaged devices out of UV light and also avoid direct exposure from strong fluorescent lights and sun light.

Certain integrated circuit (IC) manufacturing, chip-on-board (COB) and tag assembly operations may use UV light. Operations such as backgrind, de-tape, certain cleaning operations, epoxy or glue cure should be done without exposing the die surface to UV light.

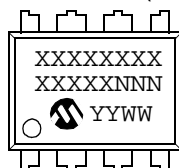
Using x-ray for die inspection will not harm the die, nor erase memory cell contents.

MCRF200

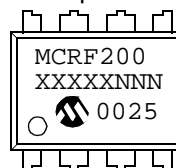
9.0 PACKAGING INFORMATION

9.1 Package Marking Information

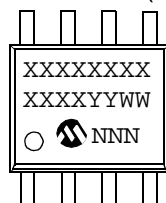
8-Lead PDIP (300 mil)



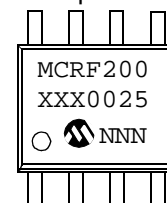
Example:



8-Lead SOIC (150 mil)



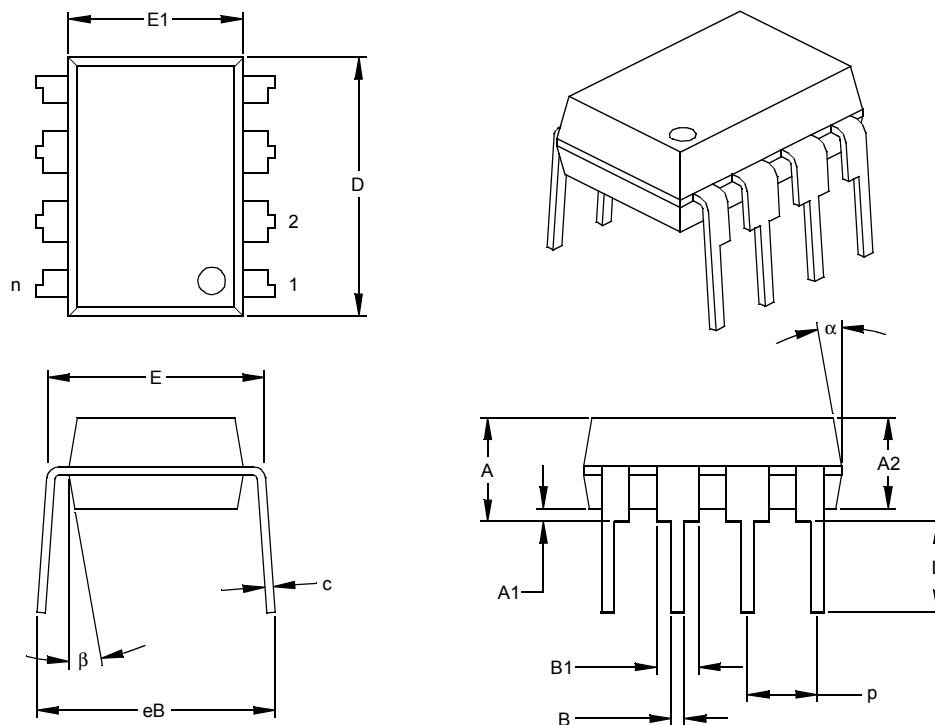
Example:



| | | |
|---|--------|--|
| Legend: | XX...X | Customer specific information* |
| | Y | Year code (last digit of calendar year) |
| | YY | Year code (last 2 digits of calendar year) |
| | WW | Week code (week of January 1 is week '01') |
| | NNN | Alphanumeric traceability code |
| Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line thus limiting the number of available characters for customer specific information. | | |

- * Standard device marking consists of Microchip part number, year code, week code, and traceability code.

8-Lead Plastic Dual In-line (P) – 300 mil (PDIP)



| UNITS | | INCHES* | | | MILLIMETERS | | |
|----------------------------|------|---------|------|------|-------------|------|-------|
| DIMENSION LIMITS | | MIN | NOM | MAX | MIN | NOM | MAX |
| Number of Pins | n | | 8 | | | 8 | |
| Pitch | p | | .100 | | | 2.54 | |
| Top to Seating Plane | A | .140 | .155 | .170 | 3.56 | 3.94 | 4.32 |
| Molded Package Thickness | A2 | .115 | .130 | .145 | 2.92 | 3.30 | 3.68 |
| Base to Seating Plane | A1 | .015 | | | 0.38 | | |
| Shoulder to Shoulder Width | E | .300 | .313 | .325 | 7.62 | 7.94 | 8.26 |
| Molded Package Width | E1 | .240 | .250 | .260 | 6.10 | 6.35 | 6.60 |
| Overall Length | D | .360 | .373 | .385 | 9.14 | 9.46 | 9.78 |
| Tip to Seating Plane | L | .125 | .130 | .135 | 3.18 | 3.30 | 3.43 |
| Lead Thickness | c | .008 | .012 | .015 | 0.20 | 0.29 | 0.38 |
| Upper Lead Width | B1 | .045 | .058 | .070 | 1.14 | 1.46 | 1.78 |
| Lower Lead Width | B | .014 | .018 | .022 | 0.36 | 0.46 | 0.56 |
| Overall Row Spacing | § eB | .310 | .370 | .430 | 7.87 | 9.40 | 10.92 |
| Mold Draft Angle Top | α | 5 | 10 | 15 | 5 | 10 | 15 |
| Mold Draft Angle Bottom | β | 5 | 10 | 15 | 5 | 10 | 15 |

* Controlling Parameter

§ Significant Characteristic

Notes:

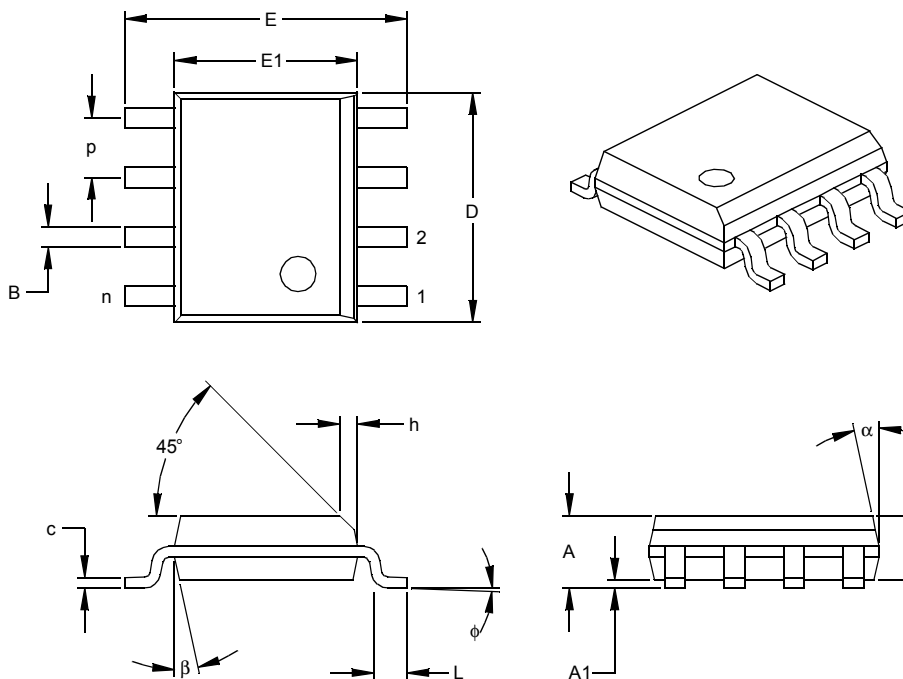
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-001

Drawing No. C04-018

MCRF200

8-Lead Plastic Small Outline (SN) – Narrow, 150 mil (SOIC)



| UNITS | | INCHES* | | | MILLIMETERS | | |
|--------------------------|----|---------|------|------|-------------|------|------|
| DIMENSION LIMITS | | MIN | NOM | MAX | MIN | NOM | MAX |
| Number of Pins | n | | 8 | | | 8 | |
| Pitch | p | | .050 | | | 1.27 | |
| Overall Height | A | .053 | .061 | .069 | 1.35 | 1.55 | 1.75 |
| Molded Package Thickness | A2 | .052 | .056 | .061 | 1.32 | 1.42 | 1.55 |
| Standoff § | A1 | .004 | .007 | .010 | .10 | .18 | .25 |
| Overall Width | E | .228 | .237 | .244 | 5.79 | 6.02 | 6.20 |
| Molded Package Width | E1 | .146 | .154 | .157 | 3.71 | 3.91 | 3.99 |
| Overall Length | D | .189 | .193 | .197 | 4.80 | 4.90 | 5.00 |
| Chamfer Distance | h | .010 | .015 | .020 | .25 | .38 | .51 |
| Foot Length | L | .019 | .025 | .030 | .48 | .62 | .76 |
| Foot Angle | φ | 0 | 4 | 8 | 0 | 4 | 8 |
| Lead Thickness | c | .008 | .009 | .010 | .20 | .23 | .25 |
| Lead Width | B | .013 | .017 | .020 | .33 | .42 | .51 |
| Mold Draft Angle Top | α | 0 | 12 | 15 | 0 | 12 | 15 |
| Mold Draft Angle Bottom | β | 0 | 12 | 15 | 0 | 12 | 15 |

* Controlling Parameter

§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-012

Drawing No. C04-057

ON-LINE SUPPORT

Microchip provides on-line support on the Microchip World Wide Web (WWW) site.

The web site is used by Microchip as a means to make files and information easily available to customers. To view the site, the user must have access to the Internet and a web browser, such as Netscape or Microsoft Explorer. Files are also available for FTP download from our FTP site.

Connecting to the Microchip Internet Web Site

The Microchip web site is available by using your favorite Internet browser to attach to:

www.microchip.com

The file transfer site is available by using an FTP service to connect to:

<ftp://ftp.microchip.com>

The web site and file transfer site provide a variety of services. Users may download files for the latest Development Tools, Data Sheets, Application Notes, User's Guides, Articles and Sample Programs. A variety of Microchip specific business information is also available, including listings of Microchip sales offices, distributors and factory representatives. Other data available for consideration is:

- Latest Microchip Press Releases
- Technical Support Section with Frequently Asked Questions
- Design Tips
- Device Errata
- Job Postings
- Microchip Consultant Program Member Listing
- Links to other useful web sites related to Microchip Products
- Conferences for products, Development Systems, technical information and more
- Listing of seminars and events

Systems Information and Upgrade Hot Line

The Systems Information and Upgrade Line provides system users a listing of the latest versions of all of Microchip's development systems software products. Plus, this line provides information on how customers can receive any currently available upgrade kits. The Hot Line Numbers are:

1-800-755-2345 for U.S. and most of Canada, and

1-480-792-7302 for the rest of the world.

013001

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

| <u>PART NO.</u> | <u>-X</u> | <u>/XXX</u> | <u>XXX</u> |
|--------------------|---|-------------|---------------|
| Device | Temperature Range | Package | Configuration |
| Device: | MCRF200 = 125 kHz Contactless Programmable MicroID tag, 96/128-bit | | |
| Temperature Range: | I = -40°C to +85°C | | |
| Package: | WF = Sawed wafer on frame (7 mil backgrind) W = Wafer (11 mil backgrind) S = Dice in wafer pack P = Plastic PDIP (300 mil Body) 8-lead SN = Plastic SOIC (150 mil Body) 8-lead 1C = 0.41 mm COB module with 1000 pF capacitor 3C = 0.41 mm COB module with 330 pF capacitor 1M = 0.40 mm (IOA2 package) COB Module w/1000 pF capacitor 3M = 0.40 mm (IOA2 package) COB Module with 330 pF capacitor | | |
| Configuration: | Three-digit hex value to be programmed into the configuration register. Three hex characters correspond to 12 binary bits. These bits are programmed into the configuration register MSB first (CB12, CB11...CB1). Refer to example. | | |

Examples:

a) MCRF200-I/W00A = 125 kHz, industrial temperature, wafer package, contactlessly programmable, 96 bit, FSK Fc/8 Fc/10, direct encoded, Fc/50 data return rate tag.

The configuration register is:

| | | | | | | | | | | | |
|------|------|------|-----|-----|-----|-----|-----|-----|-----|-----|-----|
| CB12 | CB11 | CB10 | CB9 | CB8 | CB7 | CB6 | CB5 | CB4 | CB3 | CB2 | CB1 |
| 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 1 | 0 | 1 | 0 |

Sales and Support

Data Sheets

Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office
2. The Microchip Corporate Literature Center U.S. FAX: (480) 792-7277
3. The Microchip Worldwide Site (www.microchip.com)

Please specify which device, revision of silicon and Data Sheet (include Literature #) you are using.

New Customer Notification System

Register on our web site (www.microchip.com/cn) to receive the most current information on our products.

NOTES:

Information contained in this publication regarding device applications and the like is intended through suggestion only and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. No representation or warranty is given and no liability is assumed by Microchip Technology Incorporated with respect to the accuracy or use of such information, or infringement of patents or other intellectual property rights arising from such use or otherwise. Use of Microchip's products as critical components in life support systems is not authorized except with express written approval by Microchip. No licenses are conveyed, implicitly or otherwise, under any intellectual property rights.

Trademarks


The Microchip name and logo, the Microchip logo, FilterLab, KEELOQ, microID, MPLAB, PIC, PICmicro, PICMASTER, PIC-START, PRO MATE, SEEVAL and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

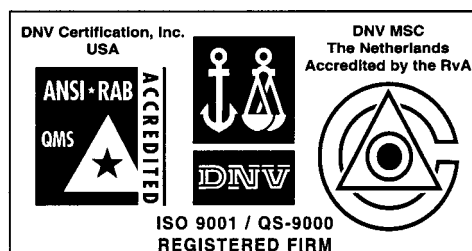
dsPIC, ECONOMONITOR, FanSense, FlexROM, fuzzyLAB, In-Circuit Serial Programming, ICSP, ICEPIC, microPort, Migratable Memory, MPASM, MPLIB, MPLINK, MPSIM, MXDEV, PICC, PICDEM, PICDEM.net, rPIC, Select Mode and Total Endurance are trademarks of Microchip Technology Incorporated in the U.S.A.

Serialized Quick Turn Programming (SQTP) is a service mark of Microchip Technology Incorporated in the U.S.A.

All other trademarks mentioned herein are property of their respective companies.

© 2002, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

 Printed on recycled paper.



Microchip received QS-9000 quality system certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona in July 1999. The Company's quality system processes and procedures are QS-9000 compliant for its PICmicro® 8-bit MCUs, KEELOQ® code hopping devices, Serial EEPROMs and microperipheral products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001 certified.



WORLDWIDE SALES AND SERVICE

AMERICAS

Corporate Office

2355 West Chandler Blvd.
Chandler, AZ 85224-6199
Tel: 480-792-7200 Fax: 480-792-7277
Technical Support: 480-792-7627
Web Address: <http://www.microchip.com>

Rocky Mountain

2355 West Chandler Blvd.
Chandler, AZ 85224-6199
Tel: 480-792-7966 Fax: 480-792-7456

Atlanta

500 Sugar Mill Road, Suite 200B
Atlanta, GA 30350
Tel: 770-640-0034 Fax: 770-640-0307

Boston

2 Lan Drive, Suite 120
Westford, MA 01886
Tel: 978-692-3848 Fax: 978-692-3821

Chicago

333 Pierce Road, Suite 180
Itasca, IL 60143
Tel: 630-285-0071 Fax: 630-285-0075

Dallas

4570 Westgrove Drive, Suite 160
Addison, TX 75001
Tel: 972-818-7423 Fax: 972-818-2924

Detroit

Tri-Atria Office Building
32255 Northwestern Highway, Suite 190
Farmington Hills, MI 48334
Tel: 248-538-2250 Fax: 248-538-2260

Kokomo

2767 S. Albright Road
Kokomo, Indiana 46902
Tel: 765-864-8360 Fax: 765-864-8387

Los Angeles

18201 Von Karman, Suite 1090
Irvine, CA 92612
Tel: 949-263-1888 Fax: 949-263-1338

New York

150 Motor Parkway, Suite 202
Hauppauge, NY 11788
Tel: 631-273-5305 Fax: 631-273-5335

San Jose

Microchip Technology Inc.
2107 North First Street, Suite 590
San Jose, CA 95131
Tel: 408-436-7950 Fax: 408-436-7955

Toronto

6285 Northam Drive, Suite 108
Mississauga, Ontario L4V 1X5, Canada
Tel: 905-673-0699 Fax: 905-673-6509

ASIA/PACIFIC

Australia

Microchip Technology Australia Pty Ltd
Suite 22, 41 Rawson Street
Epping 2121, NSW
Australia
Tel: 61-2-9868-6733 Fax: 61-2-9868-6755

China - Beijing

Microchip Technology Consulting (Shanghai)
Co., Ltd., Beijing Liaison Office
Unit 915
Bei Hai Wan Tai Bldg.
No. 6 Chaoyangmen Beidajie
Beijing, 100027, No. China
Tel: 86-10-85282100 Fax: 86-10-85282104

China - Chengdu

Microchip Technology Consulting (Shanghai)
Co., Ltd., Chengdu Liaison Office
Rm. 2401, 24th Floor,
Ming Xing Financial Tower
No. 88 TIDU Street
Chengdu 610016, China
Tel: 86-28-6766200 Fax: 86-28-6766599

China - Fuzhou

Microchip Technology Consulting (Shanghai)
Co., Ltd., Fuzhou Liaison Office
Unit 28F, World Trade Plaza
No. 71 Wusi Road
Fuzhou 350001, China
Tel: 86-591-7503506 Fax: 86-591-7503521

China - Shanghai

Microchip Technology Consulting (Shanghai)
Co., Ltd.
Room 701, Bldg. B
Far East International Plaza
No. 317 Xian Xia Road
Shanghai, 200051
Tel: 86-21-6275-5700 Fax: 86-21-6275-5060

China - Shenzhen

Microchip Technology Consulting (Shanghai)
Co., Ltd., Shenzhen Liaison Office
Rm. 1315, 13/F, Shenzhen Kerry Centre,
Renminnan Lu
Shenzhen 518001, China
Tel: 86-755-2350361 Fax: 86-755-2366086

Hong Kong

Microchip Technology Hongkong Ltd.
Unit 901-6, Tower 2, Metroplaza
223 Hing Fong Road
Kwai Fong, N.T., Hong Kong
Tel: 852-2401-1200 Fax: 852-2401-3431

India

Microchip Technology Inc.
India Liaison Office
Divyasree Chambers
1 Floor, Wing A (A3/A4)
No. 11, O'Shaughnessy Road
Bangalore, 560 025, India
Tel: 91-80-2290061 Fax: 91-80-2290062

Japan

Microchip Technology Japan K.K.
Benex S-1 6F
3-18-20, Shinyokohama
Kohoku-Ku, Yokohama-shi
Kanagawa, 222-0033, Japan
Tel: 81-45-471-6166 Fax: 81-45-471-6122

Korea

Microchip Technology Korea
168-1, Youngbo Bldg. 3 Floor
Samsung-Dong, Kangnam-Ku
Seoul, Korea 135-882
Tel: 82-2-554-7200 Fax: 82-2-558-5934

Singapore

Microchip Technology Singapore Pte Ltd.
200 Middle Road
#07-02 Prime Centre
Singapore, 188980
Tel: 65-6334-8870 Fax: 65-6334-8850

Taiwan

Microchip Technology Taiwan
11F-3, No. 207
Tung Hua North Road
Taipei, 105, Taiwan
Tel: 886-2-2717-7175 Fax: 886-2-2545-0139

EUROPE

Denmark

Microchip Technology Nordic ApS
Regus Business Centre
Lautrup hof 1-3
Ballerup DK-2750 Denmark
Tel: 45 4420 9895 Fax: 45 4420 9910

France

Microchip Technology SARL
Parc d'Activite du Moulin de Massy
43 Rue du Saule Trapu
Batiment A - 1er Etage
91300 Massy, France
Tel: 33-1-69-53-63-20 Fax: 33-1-69-30-90-79

Germany

Microchip Technology GmbH
Gustav-Heinemann Ring 125
D-81739 Munich, Germany
Tel: 49-89-627-144 0 Fax: 49-89-627-144-44

Italy

Microchip Technology SRL
Centro Direzionale Colleoni
Palazzo Taurus 1 V. Le Colleoni 1
20041 Agrate Brianza
Milan, Italy
Tel: 39-039-65791-1 Fax: 39-039-6899883

United Kingdom

Arizona Microchip Technology Ltd.
505 Eskdale Road
Winnersh Triangle
Wokingham
Berkshire, England RG41 5TU
Tel: 44 118 921 5869 Fax: 44-118 921-5820

03/01/02

